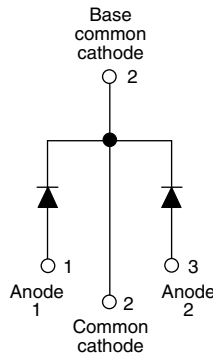


HEXFRED® Ultrafast Soft Recovery Diode, 2 x 25


TO-247AC

FEATURES

- Ultrafast and ultrasoft recovery
- Very low I_{RRM} and Q_{rr}
- Compliant to RoHS Directive 2002/95/EC
- Designed and qualified according to JEDEC-JESD47
- Halogen-free according to IEC 61249-2-21 definition (-N3 only)


BENEFITS

- Reduced RFI and EMI
- Reduced power loss in diode and switching transistor
- Higher frequency operation
- Reduced snubbing
- Reduced parts count

DESCRIPTION

VS-HFA50PA60C... is a state of the art center tap ultrafast recovery diode. Employing the latest in epitaxial construction and advanced processing techniques it features a superb combination of characteristics which result in performance which is unsurpassed by any rectifier previously available. With basic ratings of 600 V and 25 A per leg continuous current, the VS-HFA50PA60C... is especially well suited for use as the companion diode for IGBTs and MOSFETs. In addition to ultrafast recovery time, the HEXFRED® product line features extremely low values of peak recovery current (I_{RRM}) and does not exhibit any tendency to “snap-off” during the t_b portion of recovery. The HEXFRED features combine to offer designers a rectifier with lower noise and significantly lower switching losses in both the diode and the switching transistor. These HEXFRED advantages can help to significantly reduce snubbing, component count and heatsink sizes. The HEXFRED VS-HFA50PA60C... is ideally suited for applications in power supplies and power conversion systems (such as inverters), motor drives, and many other similar applications where high speed, high efficiency is needed.

PRODUCT SUMMARY

Package	TO-247AC
$I_{F(AV)}$	2 x 25 A
V_R	600 V
V_F at I_F	1.7 V
t_{rr} typ.	23 ns
T_J max.	150 °C
Diode variation	Single die

ABSOLUTE MAXIMUM RATINGS

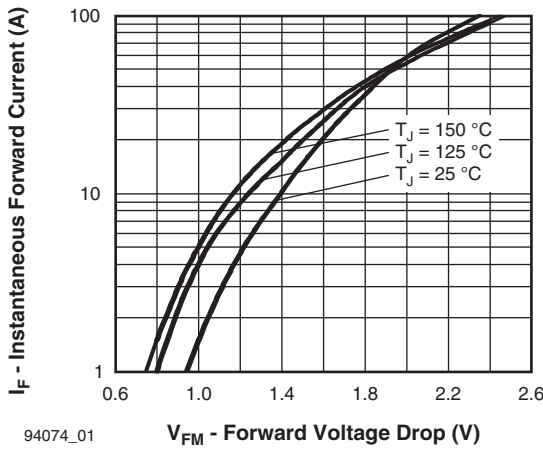
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Cathode to anode voltage	V_R		600	V
Maximum continuous forward current	I_F	$T_C = 100\text{ °C}$	per leg	25
			per device	50
Single pulse forward current	I_{FSM}		225	A
Maximum repetitive forward current	I_{FRM}		100	
Maximum power dissipation	P_D	$T_C = 25\text{ °C}$	150	W
		$T_C = 100\text{ °C}$	60	
Operating junction and storage temperature range	T_J, T_{Stg}		- 55 to + 150	°C



ELECTRICAL SPECIFICATIONS PER LEG ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Cathode to anode breakdown voltage	V_{BR}	$I_R = 100\ \mu\text{A}$	600	-	-	V
Maximum forward voltage	V_{FM}	$I_F = 25\ \text{A}$	-	1.3	1.7	
		$I_F = 50\ \text{A}$	-	1.5	2.0	
		$I_F = 25\ \text{A}, T_J = 125\text{ }^\circ\text{C}$	-	1.3	1.7	
Maximum reverse leakage current	I_{RM}	$V_R = V_R$ rated	-	1.5	20	μA
		$T_J = 125\text{ }^\circ\text{C}, V_R = 0.8 \times V_R$ rated	-	600	2000	
Junction capacitance	C_T	$V_R = 200\ \text{V}$	-	55	100	pF
Series inductance	L_S	Measured lead to lead 5 mm from package body	-	12	-	nH

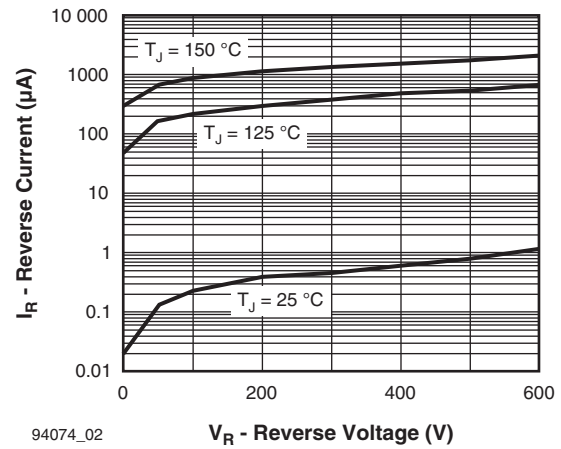
DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time See fig. 5, 10	t_{rr}	$I_F = 1.0\ \text{A}, di_F/dt = 200\ \text{A}/\mu\text{s}, V_R = 30\ \text{V}$	-	23	-	ns
	t_{rr1}	$T_J = 25\text{ }^\circ\text{C}$	-	50	75	
	t_{rr2}	$T_J = 125\text{ }^\circ\text{C}$	-	105	160	
Peak recovery current See fig. 6	I_{RRM1}	$T_J = 25\text{ }^\circ\text{C}$	-	4.5	10	A
	I_{RRM2}	$T_J = 125\text{ }^\circ\text{C}$	-	8.0	15	
Reverse recovery charge See fig. 7	Q_{rr1}	$T_J = 25\text{ }^\circ\text{C}$	-	112	375	nC
	Q_{rr2}	$T_J = 125\text{ }^\circ\text{C}$	-	420	1200	
Peak rate of fall of recovery current during t_b See fig. 8	$di_{(rec)M}/dt1$	$T_J = 25\text{ }^\circ\text{C}$	-	250	-	$\text{A}/\mu\text{s}$
	$di_{(rec)M}/dt2$	$T_J = 125\text{ }^\circ\text{C}$	-	160	-	

THERMAL - MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Lead temperature	T_{lead}	0.063" from case (1.6 mm) for 10 s	-	-	300	$^\circ\text{C}$
Junction to case, single leg conducting	R_{thJC}		-	-	0.83	K/W
Junction to case, both legs conducting			-	-	0.42	
Thermal resistance, junction to ambient	R_{thJA}	Typical socket mount	-	-	40	
Thermal resistance, case to heatsink	R_{thCS}	Mounting surface, flat, smooth and greased	-	0.25	-	
Weight			-	6.0	-	g
			-	0.21	-	oz.
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-247AC	HFA50PA60C			



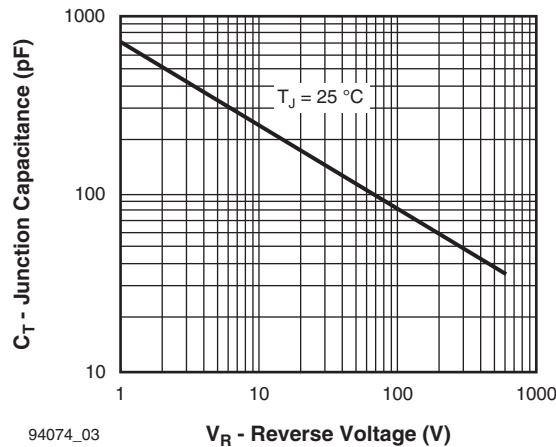
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Fig. 1 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current (Per Leg)



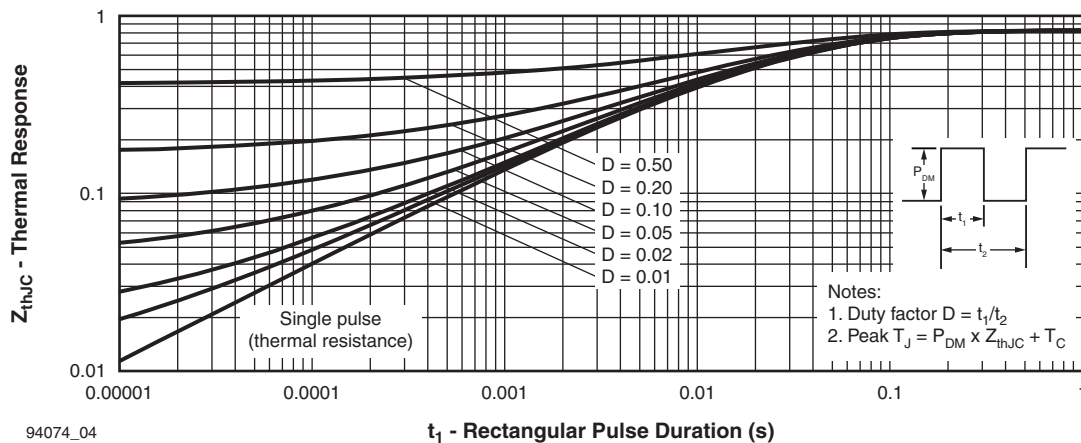
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Fig. 2 - Typical Reverse Current vs. Reverse Voltage (Per Leg)



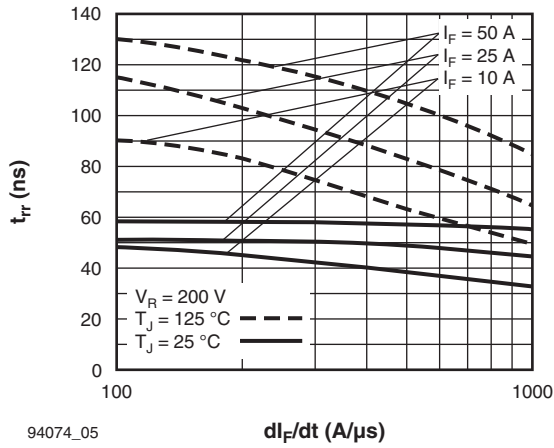
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Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage (Per Leg)



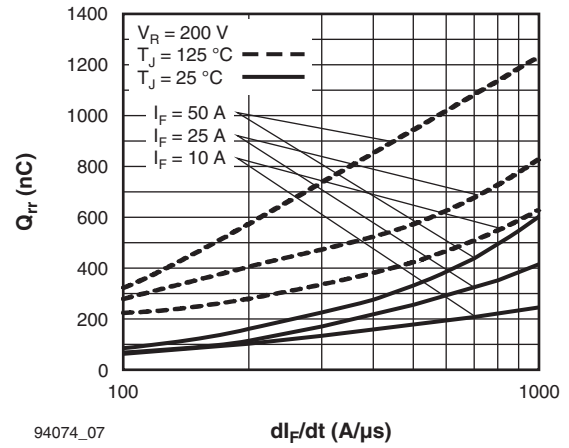
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Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics (Per Leg)



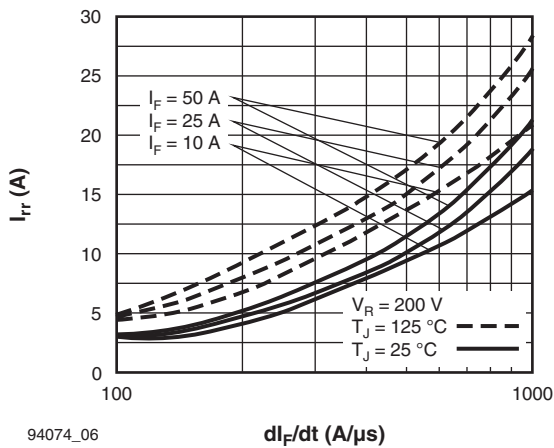
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Fig. 5 - Typical Reverse Recovery Time vs. di_F/dt (Per Leg)



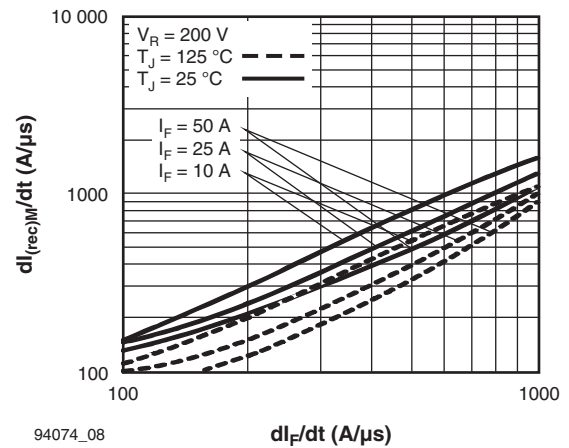
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Fig. 7 - Typical Stored Charge vs. di_F/dt (Per Leg)



94074_06

Fig. 6 - Typical Recovery Current vs. di_F/dt (Per Leg)



94074_08

Fig. 8 - Typical $di_{(rec)M}/dt$ vs. di_F/dt (Per Leg)

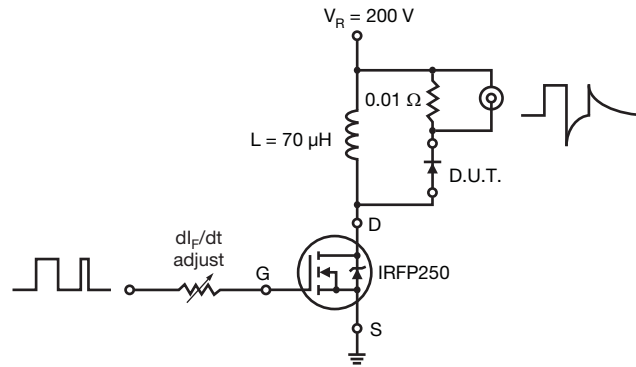
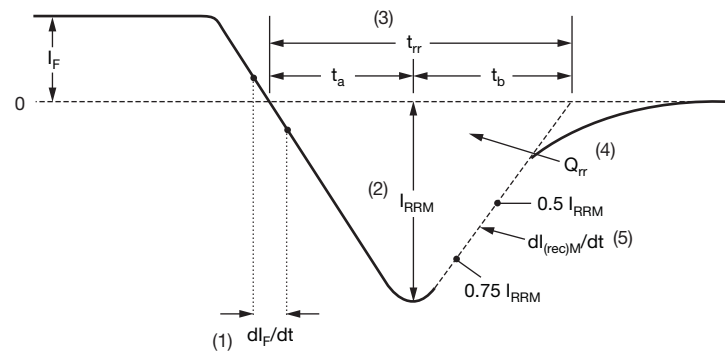


Fig. 9 - Reverse Recovery Parameter Test Circuit



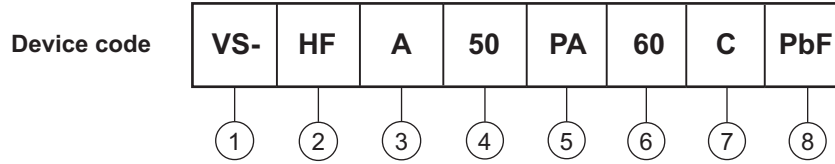
- (1) dI_F/dt - rate of change of current through zero crossing
- (2) I_{RRM} - peak reverse recovery current
- (3) t_{rr} - reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through $0.75 I_{RRM}$ and $0.50 I_{RRM}$ extrapolated to zero current.
- (4) Q_{rr} - area under curve defined by t_{rr} and I_{RRM}
- (5) $dI_{(rec)M}/dt$ - peak rate of change of current during t_b portion of t_{rr}

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 10 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - HEXFRED® family
- 3** - Electron irradiated
- 4** - Current rating (50 = 50 A)
- 5** - PA = TO-247AC
- 6** - Voltage rating: (60 = 600 V)
- 7** - Circuit configuration
C = Common cathode
- 8** - Environmental digit:
PbF = Lead (Pb)-free and RoHS compliant
-N3 = Halogen-free, RoHS compliant and totally lead (Pb)-free

ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-HFA50PA60CPbF	25	500	Antistatic plastic tube
VS-HFA50PA60C-N3	25	500	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS		
Dimensions		www.vishay.com/doc?95223
Part marking information	TO-247ACPbF	www.vishay.com/doc?95226
	TO-247AC-N3	www.vishay.com/doc?95007

TO-220AC

DIMENSIONS in millimeters and inches



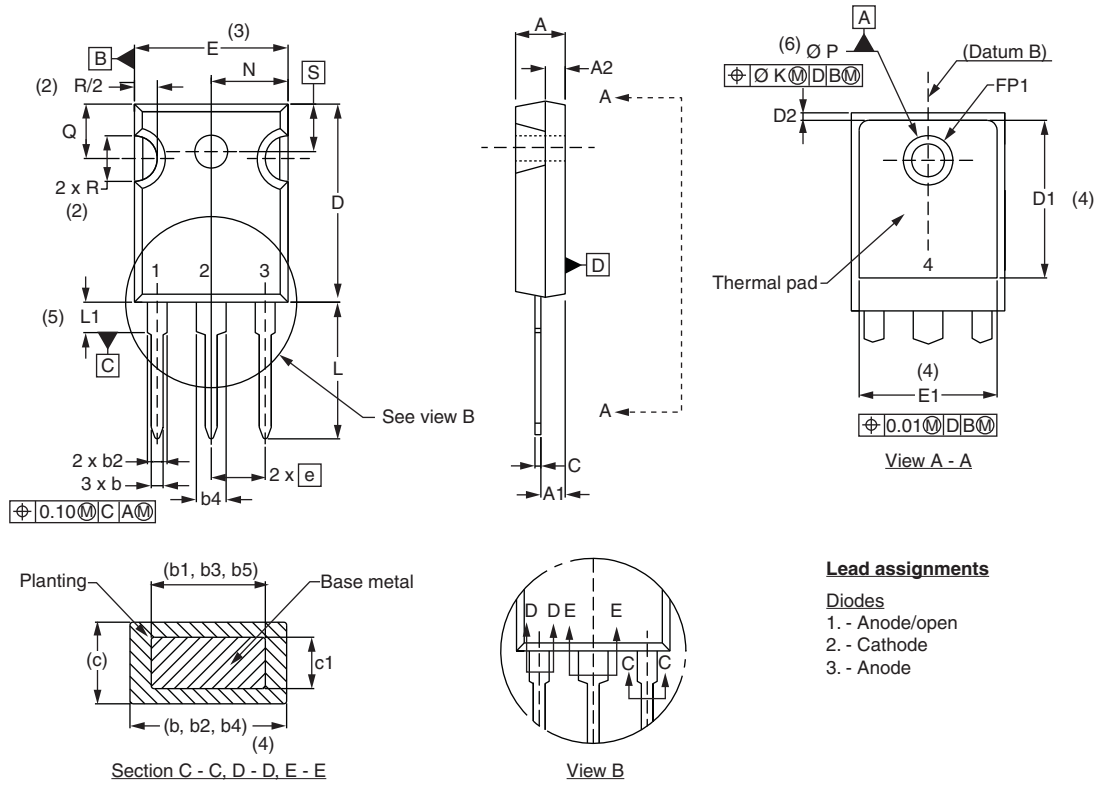
SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183		E1	6.86	8.89	0.270	0.350	6
A1	1.14	1.40	0.045	0.055		E2	-	0.76	-	0.030	7
A2	2.56	2.92	0.101	0.115		e	2.41	2.67	0.095	0.105	
b	0.69	1.01	0.027	0.040		e1	4.88	5.28	0.192	0.208	
b1	0.38	0.97	0.015	0.038	4	H1	6.09	6.48	0.240	0.255	6, 7
b2	1.20	1.73	0.047	0.068		L	13.52	14.02	0.532	0.552	
b3	1.14	1.73	0.045	0.068	4	L1	3.32	3.82	0.131	0.150	2
c	0.36	0.61	0.014	0.024		L3	1.78	2.13	0.070	0.084	
c1	0.36	0.56	0.014	0.022	4	L4	0.76	1.27	0.030	0.050	2
D	14.85	15.25	0.585	0.600	3	Ø P	3.54	3.73	0.139	0.147	
D1	8.38	9.02	0.330	0.355		Q	2.60	3.00	0.102	0.118	
D2	11.68	12.88	0.460	0.507	6	θ	90° to 93°		90° to 93°		
E	10.11	10.51	0.398	0.414	3, 6						

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC TO-220, D2 (minimum) where dimensions are derived from the actual package outline



DIMENSIONS in millimeters and inches



Lead assignments

- Diodes**
 1. - Anode/open
 2. - Cathode
 3. - Anode

SYMBOL	MILLIMETERS		INCHES		NOTES	SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.			MIN.	MAX.	MIN.	MAX.	
A	4.65	5.31	0.183	0.209		D2	0.51	1.30	0.020	0.051	
A1	2.21	2.59	0.087	0.102		E	15.29	15.87	0.602	0.625	3
A2	1.50	2.49	0.059	0.098		E1	13.72	-	0.540	-	
b	0.99	1.40	0.039	0.055		e	5.46 BSC		0.215 BSC		
b1	0.99	1.35	0.039	0.053		FK	2.54		0.010		
b2	1.65	2.39	0.065	0.094		L	14.20	16.10	0.559	0.634	
b3	1.65	2.37	0.065	0.094		L1	3.71	4.29	0.146	0.169	
b4	2.59	3.43	0.102	0.135		N	7.62 BSC		0.3		
b5	2.59	3.38	0.102	0.133		ΦP	3.56	3.66	0.14	0.144	
c	0.38	0.86	0.015	0.034		ΦP1	-	6.98	-	0.275	
c1	0.38	0.76	0.015	0.030		Q	5.31	5.69	0.209	0.224	
D	19.71	20.70	0.776	0.815	3	R	4.52	5.49	1.78	0.216	
D1	13.08	-	0.515	-	4	S	5.51 BSC		0.217 BSC		

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC outline TO-247 with exception of dimension c



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